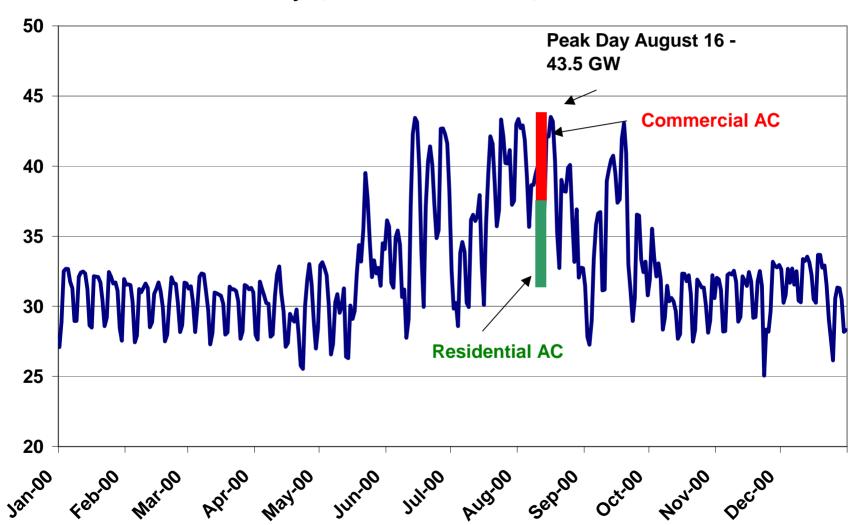


The California Challenge



Cal ISO Daily Peak Loads

January 1, 2000 - December 31, 2000





Options



- * Supply-side solutions (building more power plants in our back garden!) to provide for peak demand or system emergencies cost up to 10x more than some demand-side solutions
- * In 2000-1, less than 5% "automated" load reduction could have avoided blackouts
- * Air conditioning is the 'low-hanging fruit'
- * A real-time control and communications infrastructure is required to support an automated demand response (DR) system

Courtesy: Ron Hofmann





Demand Response

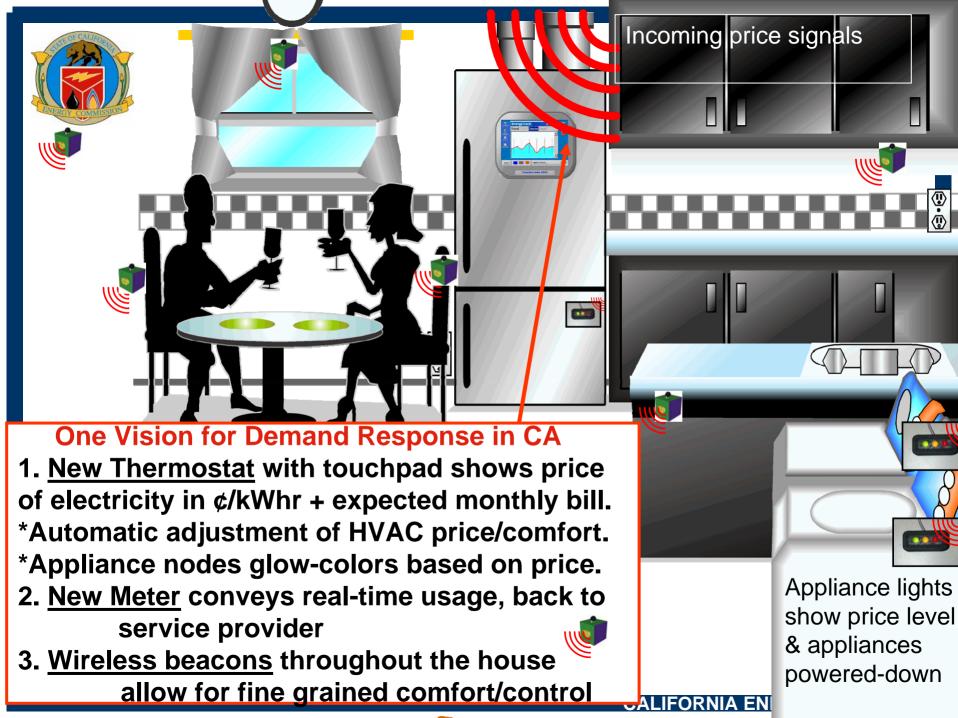
- * Demand response (DR) is the action taken to reduce load when:
 - Contingencies (emergencies & congestion) occur that threaten supply-demand balance, and/or
 - Market conditions occur that raise supply costs
- * DR typically involves peak-load reductions
 - DR strategies are different from energy efficiency, i.e., transient vs. permanent

Courtesy: Ron Hofmann



DR ETD – Summary of New Thermostat, TempNode, & New Meter (UC Berkeley Project 6/6/06)

- New Thermostat, New Temperature Node, & New Meter
- * Phase One: 3/2003 8/2005; Phase Two 9/2005 8/2007
- * Multi-disciplinary Collaboration Team:
 - David Auslander: ME Dept.
 - Ed Arens & Charlie Huizenga: Center for Built Environment
 - Kris Pister: Berkeley Sensor & Actuator Center, EECS Dept.
 - Jan Rabaey: Berkeley Wireless Research Center, EECS Dept
 - Dick White: Berkeley Sensor & Actuator Center, EECS Dept.
 - Paul Wright: Berkeley Manufacturing Institute, ME Dept.
 - 20 Graduate Student Researchers (13 are funded)
 - Many thanks to all colleagues and students for their contributions

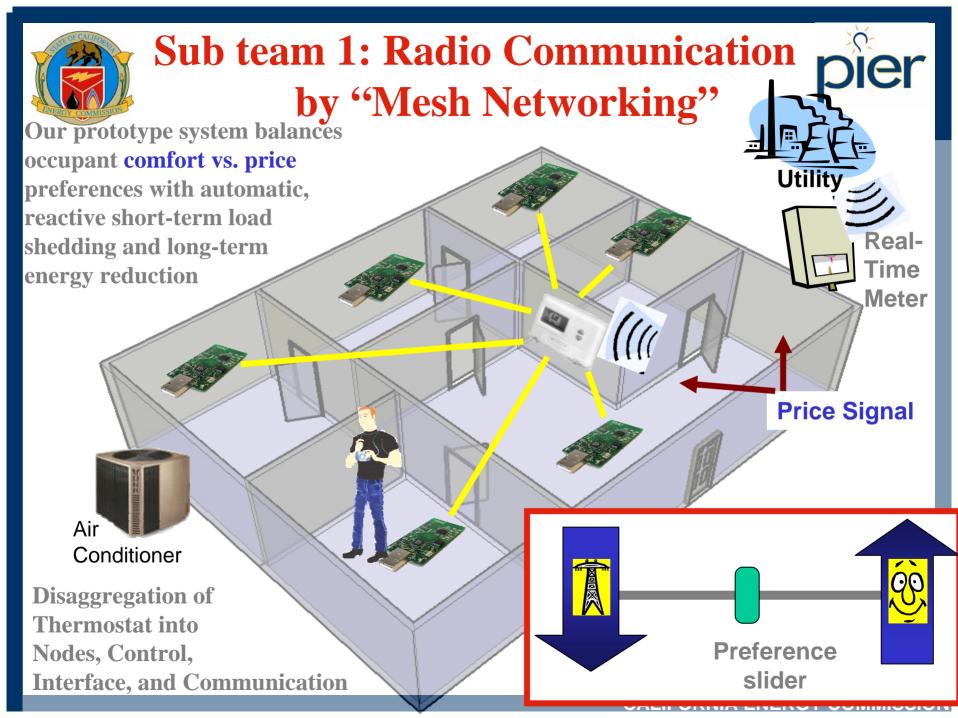




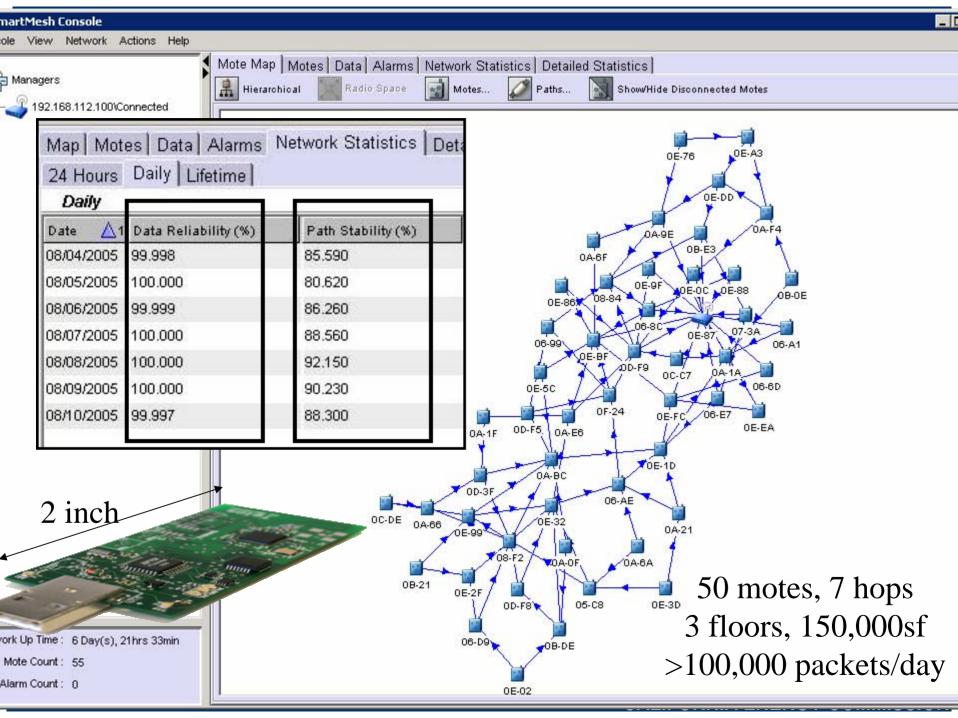
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DR ETD Project Overview

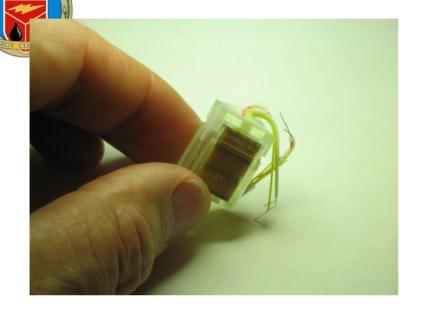
- * Mid- to long-term R&D (3-8 year objectives)
 - To help achieve a DR Infrastructure in California
- * Enabling technologies R&D with 10x10x10 goals not product development
- * Multi-disciplinary with 4 collaborative sub-teams
 - 1. Communication 2. Control 3. Sensing 4. Power Supply
 - Leverage DARPA, DoE, NSF, Intel, and other funding
- * "Disruptive" 10x10x10 improvements, e.g...
 - 1. Tiny OS (ad hoc self organizing networks) Pico radio (low-cost, low-power wireless)
 - 2. Learning algorithms (individualized DR response)
 - 3. Smart Dust (highly integrated control platform)
 - 4. Energy Scavenging (avoid replaceable batteries)



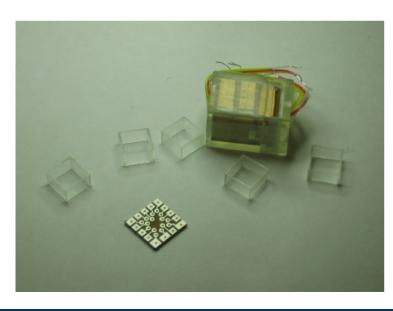
Hardware used with today's Telos 06 device	WeC 1998	René 1999	René 2 2000	Dot 2000	Mica 2001	Mica2Dot 2002	Mica 2 2002	Telos 2004
Microcontroller								
Type	AT90LS8535			ega163	ATmega128			TI MSP430
Program memory (KB)	8	8 16			128			60
RAM (KB)	0.5		1		4			2
Active Power (mW)	15		15		8		33	3
Sleep Power (µW)	45		45		75		75	6
Wakeup Time (μs)	1000	36		180		180	6	
Nonvolatile storage								
Chip	24LC256				AT45DB041B			ST M24M01S
Connection type	I ² C				SPI			I ² C
Size (KB)	32				512			128
Communication		72220	4.542.752				/ P. s. P. s.	
Radio	TR1000				TR1000	CC1000		CC2420
Data rate (kbps)	10				40	38.4		250
Modulation type	OOK				ASK	F:	SK	O-QPSK
Receive Power (mW)	9				12	29		38
Transmit Power at 0dBm (mW)	36				36	42		35
Power Consumption								
Minimum Operation (V)	2.7		2	7		2.7		1.8
Total Active Power (mW)		24			27	44	89	41
Programming and Sensor Interfac	e							
Expansion	none	51-pin	51-pin	none	51-pin	19-pin	51-pin	10-pin
Communication	IEEE 1284 (programming) and RS232 (requires additional hardware)							USB
Integrated Sensors	no	no	no	yes	no	no	no	yes

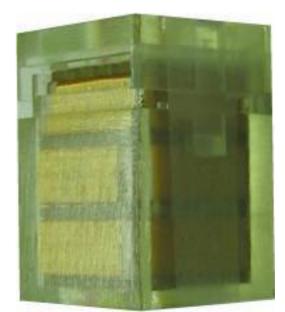


Towards 10x lower cost: PicoCube Prototype Dier





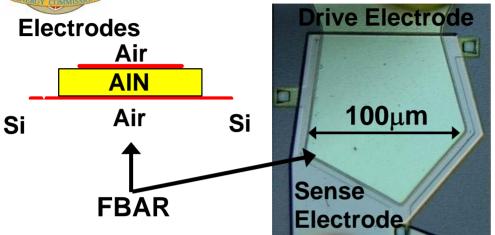






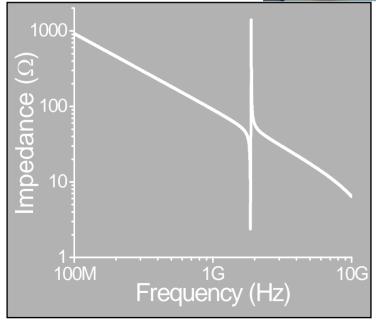
Extensive Use of Innovative MEMS



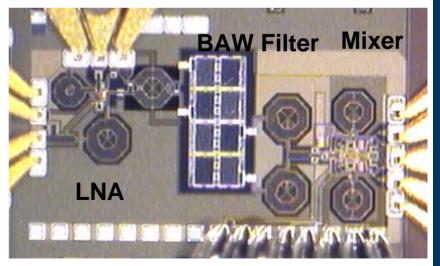


Small form factor

- MEMS/CMOS co-design
- Integration into IC process



Ruby et. al. (Ultrasonics Symposium 2001)



Carpentier et. al. (ISSCC 2005)





Two radio projects both aiming at 10x10?

- * "FBAR route" explores new MEMS technology for design (uses OOK)
- * Pros:
 - Simple design with MEMS simplifies oscillator
 - Fixed at one frequency
 - Will get to lower power levels

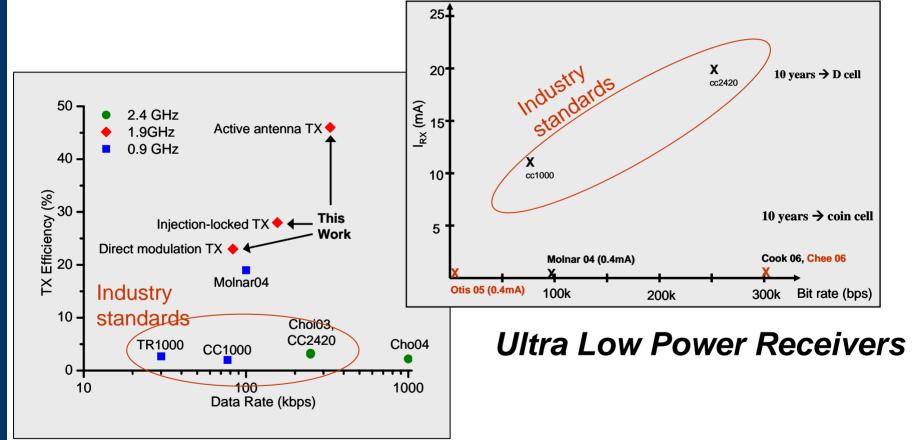
- * "CMOS optimized" using passive gain thru LC network (uses FSK)
- * Pros:
 - Standard CMOS
 - Tuneable (1.9-2.4 GHz)
 - Robust with noise linearity similar to commercial devices
 - More flexible design

Courtesy: J. Rabaey, K. Pister



Radio Performance summary and the exciting year(s) ahead





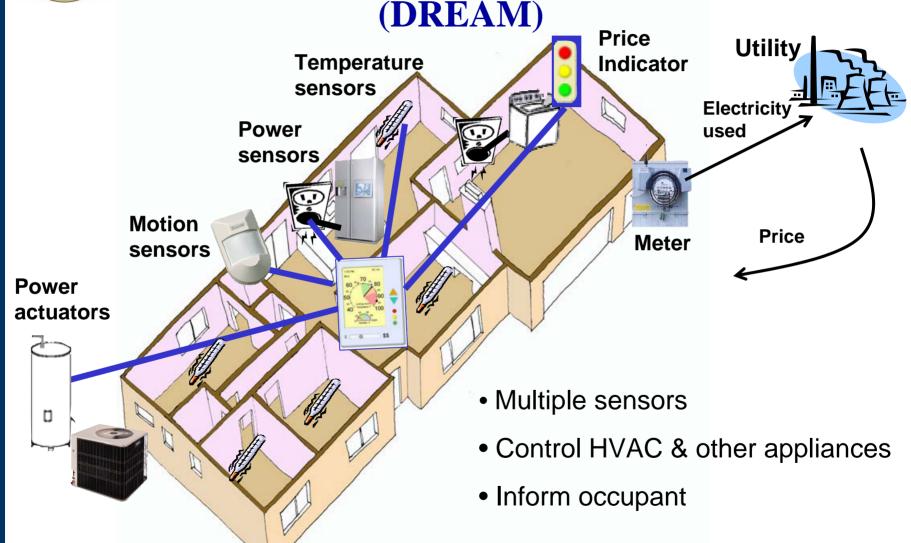
0 dbM Transmitters

Courtesy: J. Rabaey, K. Pister



Demand Response Electrical Appliance Manager



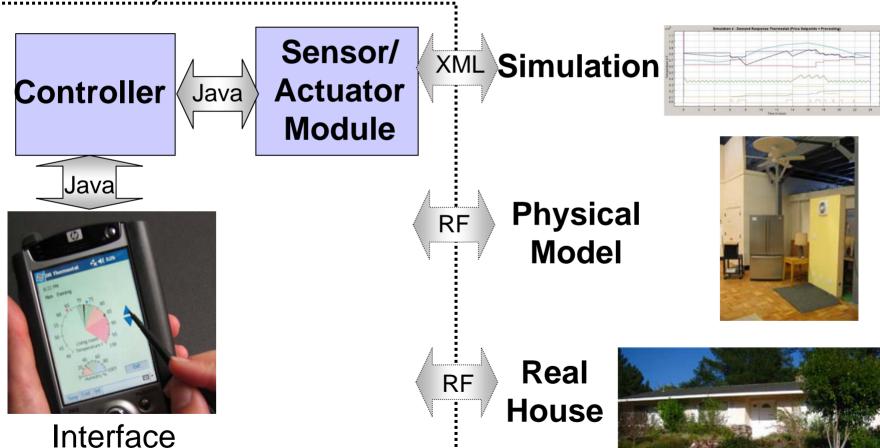




DREAM Control Code



Control of simulated, model, or real houses

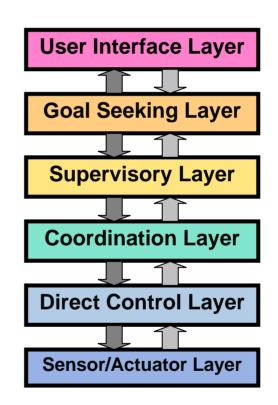




System Control



- * Layered control
- * Used to build control software for experiments to-date
- * Next challenge:
 - Autonomous behavior

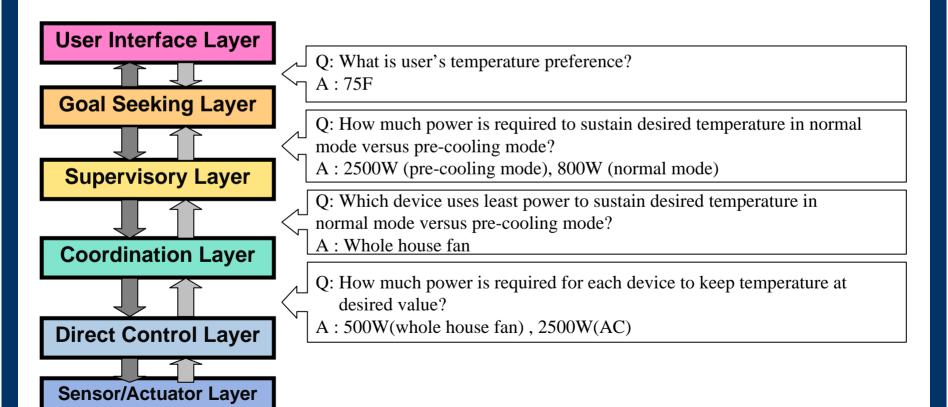








Assessing potential for precooling

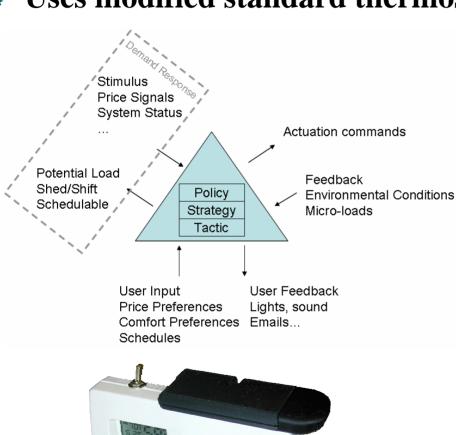




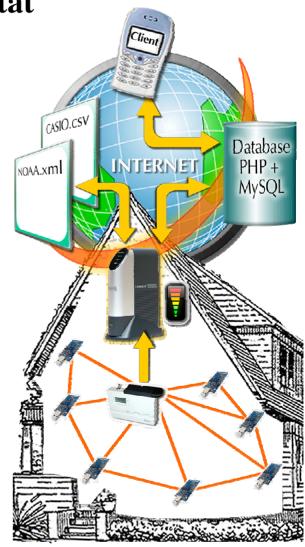
The Residential Energy Manager



Uses modified standard thermostat



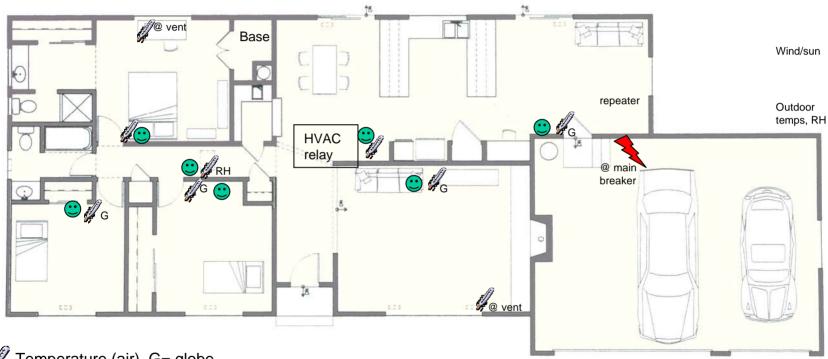












Temperature (air), G= globe Temperature (air) + RH

Occupancy

Nower sensing (breaker panel)

Weather station on roof (not shown)
Anemometer (wind direction and speed)
Pyranometer (total horizontal radiation and diffuse radiation)
Outside Temperature (exposed to night sky, not exposed)
Outside RH

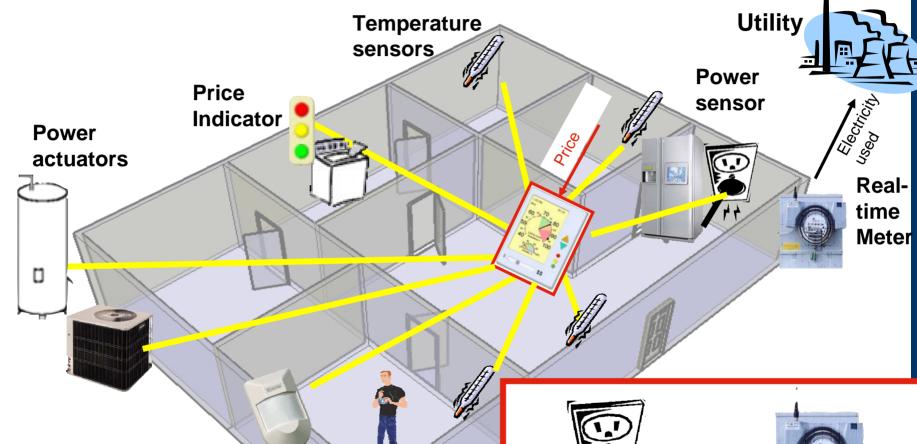


Occupancy

sensors

Sub-team #3: Sensors for Metering and Monitoring







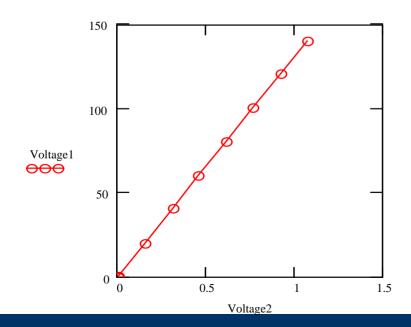


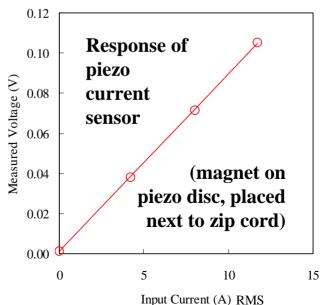
Metering and Monitoring

Challenge: Make sensors for AC voltage and AC current that are passive and operate in close proximity to insulated AC wiring? Passive so they don't require DC power source (replaceable batteries) Proximity so we don't have make conductive contact to wiring

AC Voltage sensor: Electrostatically couple electrodes near insulated wires and detect using analog/digital converter on wireless mote for transmission:

AC current sensor: Locate piezoelectrically-coated cantilever with attached magnetic material near current-carrying insulated wires. Output voltage is proportional to peak electric current.

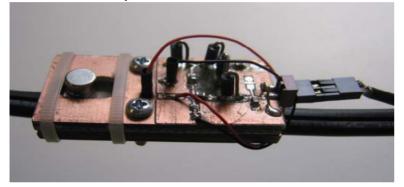




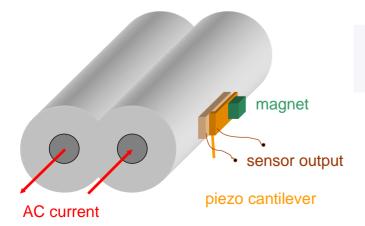
CALIFORNIA ENERGY C

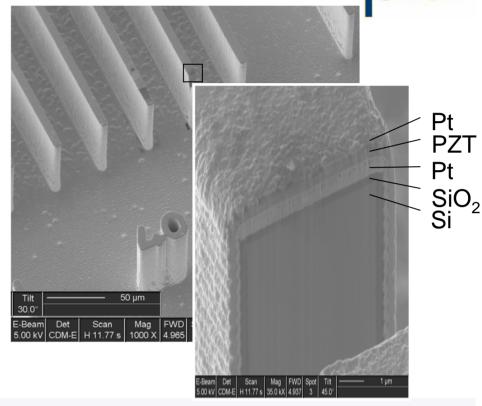
Proximity Current Sensor

Meso-scale current sensors on zipcord with permanent magnet on cantilever coated with piezoelectric



Proposed MEMS-based AC current sensor



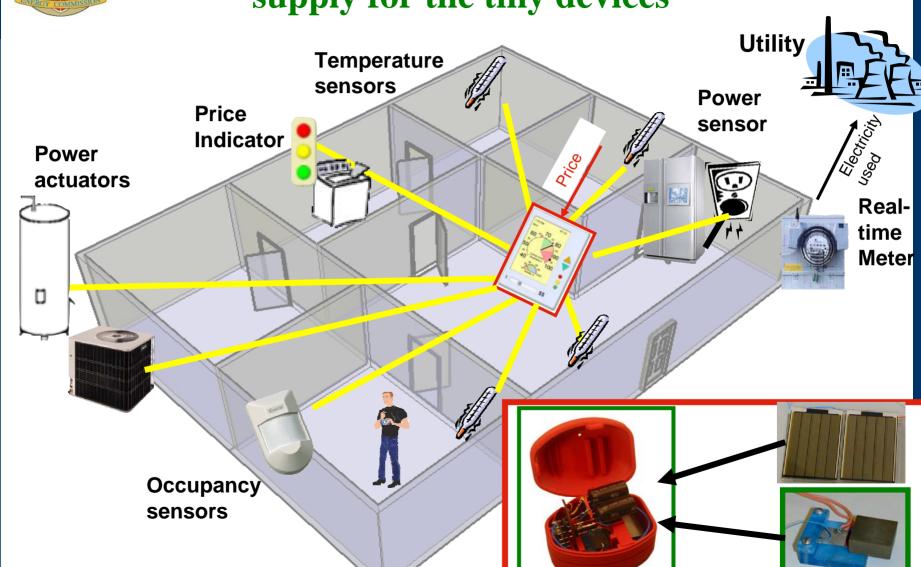


PZT film on sidewalls creates piezoelectric bimorph structure



Sub-team #4: The power supply for the tiny devices



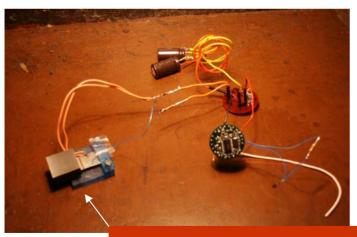




Environmental vibrations







- Stair-Case Vibrations from Running Up and Down Stairs
- * Piezoelectric: PZT
- Tungsten Alloy Mass: 52 g
- * Beam Dimensions:
- * 1.25" x 0.5" x 0.02"
- * Resonant Frequency: 26.8 Hz
- * Power Output: 450 μW

Piezoelectric "diving board" with tungsten mass



Cost reduction @ MEMS scale Piezoelectric and Elastic Layers





1. SrTiO₃ (STO) coated (10 nm) single crystal Silicon [Motorola, Inc.]

2. Deposition of SrRuO₃ (SRO) bottom electrode, and PZT with pulsed laser deposition.

Elastic Layer Deposition Methods

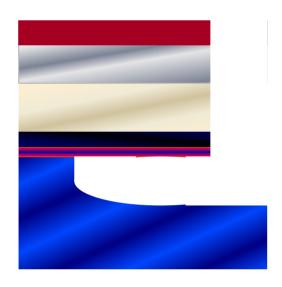
- *Pt- electron beam evaporation, Ti adhesion layer
- *Ni- thermal evaporation
- *Au- electron beam/thermal evaporation, Cr adhesion layer

3. Deposition of metallic elastic layer via e-beam evaporation/thermal evaporation



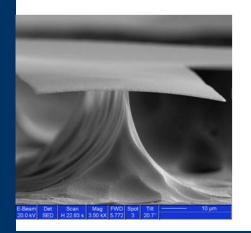
MEMS scale Cantilever Array Structures

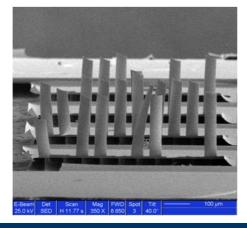


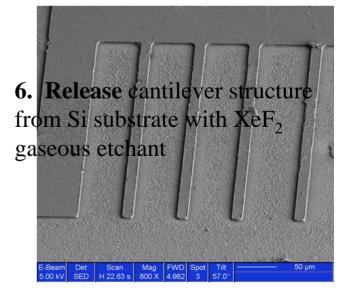


4. Definition of devices using photolithography

5. Etch heterostructure with Ar ion milling to expose Si substrate



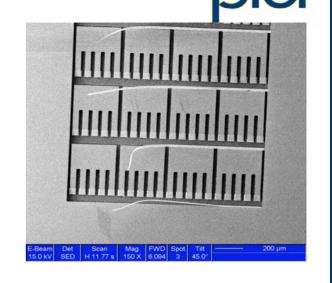


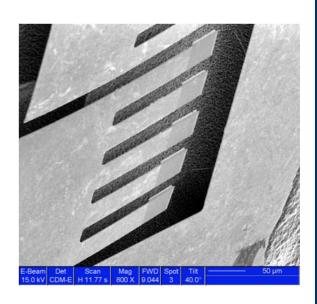


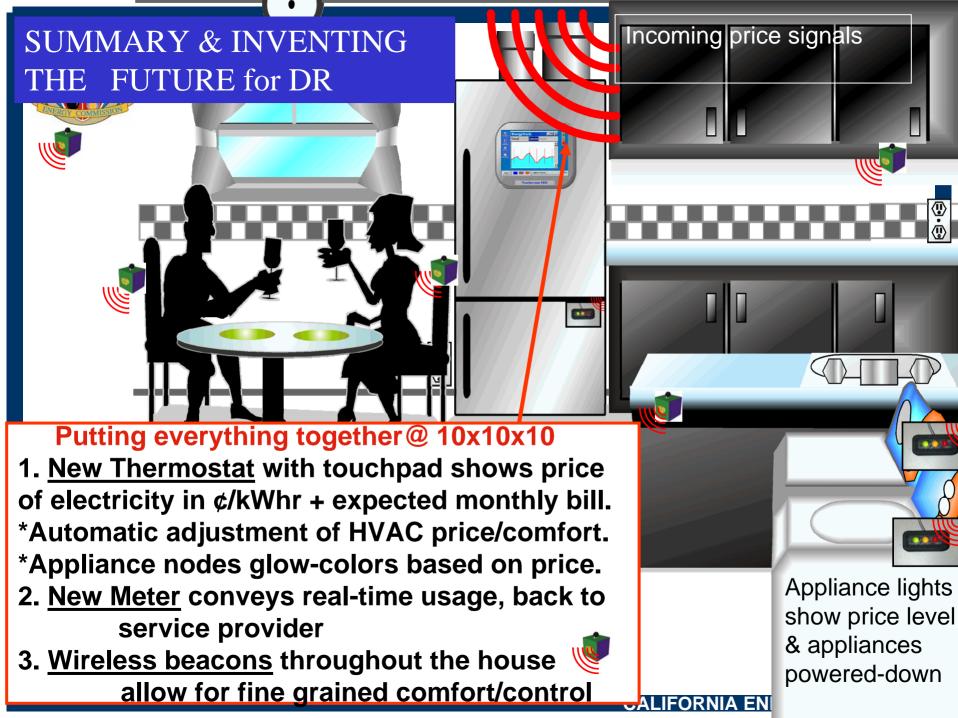


MEMS Findings for Power Supply

- * Pulsed laser deposition can be used to grow epitaxial PZT films on Si substrate
- * Thin film piezoelectric coefficient approaches bulk values, shows good switching capabilities
- * Microscale cantilever resonant frequency 250-2500 Hertz, alternative design increase frequency
- * Power modeling indicates a power density approaching 200 μ W/cm³
- * Cantilever arrays fabricated and released using standard-CMOS compatible processes
- * Residual stresses in film reduced



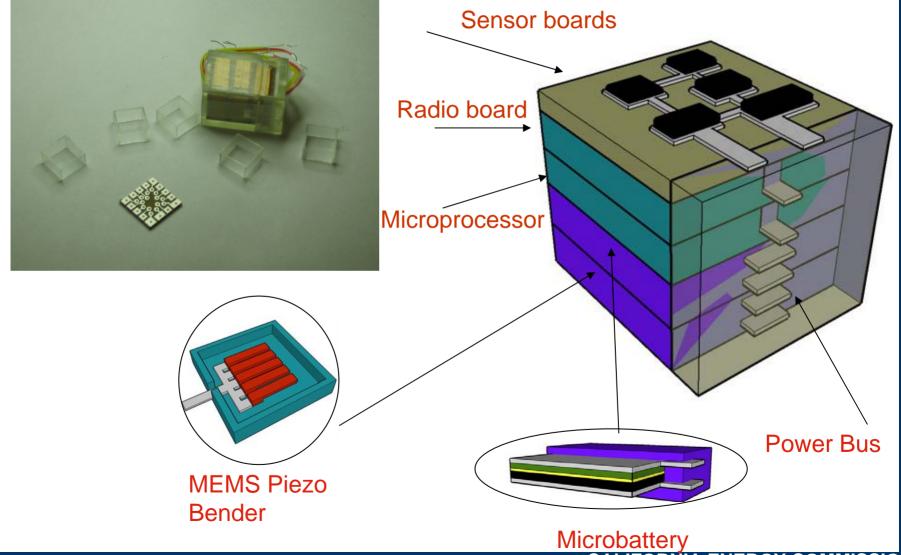






Beginning micro-integration and miniaturization to reduce DR's cost Pier





CALIFORNIA ENERGY COMMISSION





DR Summary

- Managing our summer peaks today is as big a job for society as was managing our per capita energy (kW-hr) needs in the last quarter of the 20th century
- * However, this problem is different in that it involves complex information exchange and advanced communication systems
- * Such communication needs the micro-integration of
 - Low-power radios,
 - Mesh-networking,
 - MEMS-scale sensing,
 - MEMS scale power supplies, and
 - Micro-packaging-integration
 - All at "about a couple of dollars BOM per platform" range.
- * Such micro-integration will enable DR control and learning, for integration into meters, thermostats, temperature nodes





Thanks to....

- * Of course, PIER/CEC
- * Wireless Sensor Network suppliers
 - Crossbow Inc. in San Jose CA
 - Dust Networks in Freemont CA
 - Moteiv in Berkeley CA
- Wafers and chip prototyping
 - Motorola
 - ST Microelectronics
- * Related industrial sponsors
 - Honeywell
 - Alcoa





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